

N-Channel Power MOSFET

700V, 4.5A, 0.9Ω

FEATURES

- Super-Junction technology
- High performance due to small figure-of-merit
- High ruggedness performance
- High commutation performance

ΔD	DI	IC.	LT I	ON

- Power Supply
- Lighting

KEY PERFORMANCE PARAMETERS				
PARAMETER VALUE UNIT				
V_{DS}	700	V		
R _{DS(on)} (max)	0.9	Ω		
Q _g	9.7	nC		



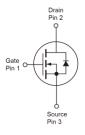












Notes: MSL 3 (Moisture Sensitivity Level) for TO-252 (DPAK) per J-STD-020.

ABSOLUTE MAXIMUM RATINGS (T _C = 25°C unless otherwise noted)						
PARAMETER		SYMBOL	IPAK/DPAK	ITO-220	UNIT	
Drain-Source Voltage		V_{DS}	700		V	
Gate-Source Voltage		V_{GS}	±30		V	
Continuous Drain Current (Note 1)	$T_C = 25^{\circ}C$		4.5 2.7			
Continuous Drain Current	$T_C = 100$ °C	l _D			Α	
Pulsed Drain Current (Note 2)		I _{DM}	13.5		Α	
Total Power Dissipation @ T _C = 25°C		P _{DTOT}	50	20	W	
Single Pulsed Avalanche Energy (Note 3)		E _{AS}	64		mJ	
Single Pulsed Avalanche Current (Note 3)		I _{AS}	1.6		Α	
Operating Junction and Storage Temperature Range		T_J, T_{STG}	- 55 to +150		°C	

THERMAL PERFORMANCE					
PARAMETER	SYMBOL	IPAK/DPAK	ITO-220	UNIT	
Junction to Case Thermal Resistance	R _{eJC}	c 2.5 6.25		°C/W	
Junction to Ambient Thermal Resistance	$R_{\Theta JA}$	62		°C/W	

Notes: $R_{\Theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins. $R_{\Theta JA}$ is guaranteed by design while $R_{\Theta CA}$ is determined by the user's board design. $R_{\Theta JA}$ shown below for single device operation on FR-4 PCB in still air.





ELECTRICAL SPECIFICATIONS (T _C = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static (Note 4)						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV _{DSS}	700			V
Gate Threshold Voltage	$V_{DS} = V_{GS}, \ I_D = 250 \mu A$	$V_{GS(TH)}$	2.0	3.1	4.0	V
Gate Body Leakage	$V_{GS}=\pm30V,V_{DS}=0V$	I _{GSS}			±100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 700V, V_{GS} = 0V$	I _{DSS}			1	μΑ
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 1.5A$	R _{DS(on)}		0.83	0.9	Ω
Dynamic (Note 5)						
Total Gate Charge	.,	Q_g		9.7		
Gate-Source Charge	$V_{DS} = 380V, I_{D} = 2.3A,$	Q _{gs}		2.9		nC
Gate-Drain Charge	$V_{GS} = 10V$	Q_{gd}		3.5		
Input Capacitance	$V_{DS} = 100V, V_{GS} = 0V,$	C _{iss}		482		_
Output Capacitance	f = 1.0MHz	C _{oss}		34		pF
Gate Resistance	F = 1MHz, open drain	R_g		3.6		Ω
Switching (Note 6)						
Turn-On Delay Time		t _{d(on)}		20		
Turn-On Rise Time	$V_{DD} = 380V,$ $R_{GEN} = 40\Omega,$ $I_{D} = 2.3A, V_{GS} = 10V,$	t _r		54		
Turn-Off Delay Time		t _{d(off)}		34		ns
Turn-Off Fall Time	$I_{D} = 2.3A, V_{GS} = 10V,$	t _f		48		
Source-Drain Diode (Note 4)						
Forward On Voltage	$I_S = 4.5A, V_{GS} = 0V$	V _{SD}			1.4	V
Reverse Recovery Time	V _B =200V, I _S = 2.3A	t _{rr}		176		ns
Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	Q _{rr}		1.1		μC

Notes:

- 1. Current limited by package
- 2. Pulse width limited by the maximum junction temperature
- 3. L = 50mH, $I_{AS} = 1.6A$, $V_{DD} = 50V$, $R_G = 25\Omega$, Starting $T_J = 25^{\circ}C$
- 4. Pulse test: PW \leq 300 μ s, duty cycle \leq 2%
- 5. For DESIGN AID ONLY, not subject to production testing.
- 6. Switching time is essentially independent of operating temperature.





ORDERING INFORMATION

ORDERING CODE	PACKAGE	PACKING
TSM70N900CI C0G	ITO-220	50pcs / Tube
TSM70N900CH C5G	TO-251 (IPAK)	75pcs / Tube
TSM70N900CP ROG	TO-252 (DPAK)	2,500pcs / 13" Reel

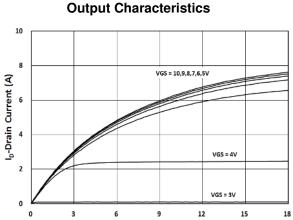
Note:

- 1. Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- 2. Halogen-free according to IEC 61249-2-21 definition

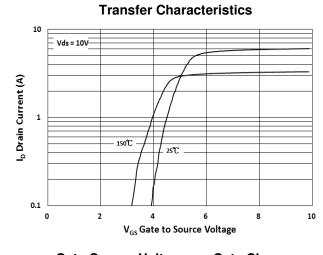


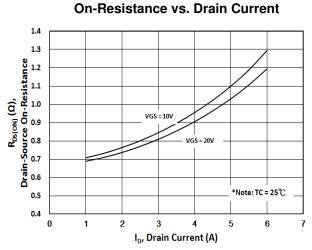
CHARACTERISTICS CURVES

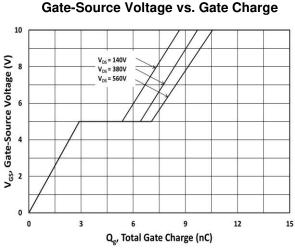
 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$

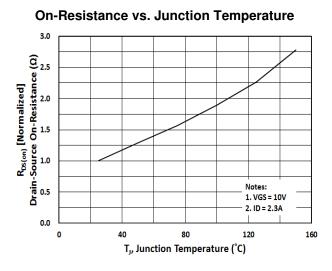


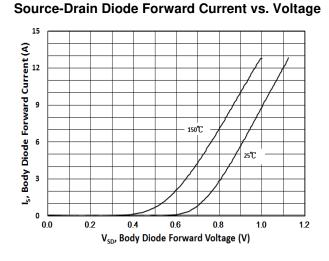
V_{DS}-Drain to Source Voltage (V)









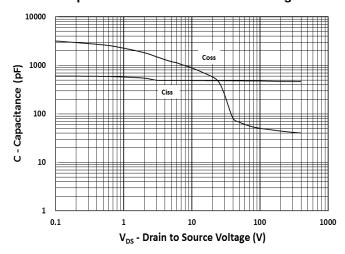




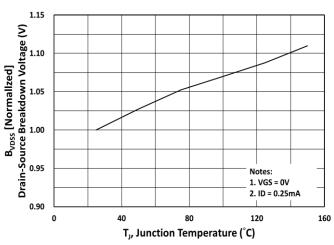
CHARACTERISTICS CURVES

(T_C = 25°C unless otherwise noted)

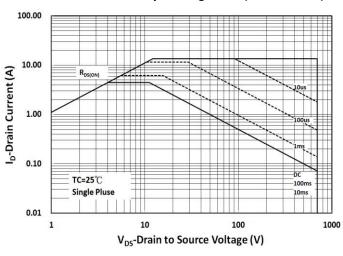
Capacitance vs. Drain-Source Voltage



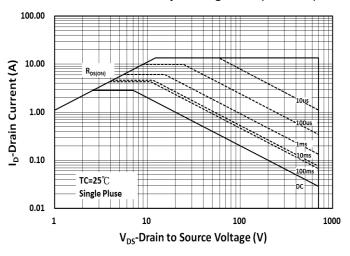
BV_{DSS} vs. Junction Temperature



Maximum Safe Operating Area (DPAK/IPAK)



Maximum Safe Operating Area (ITO-220)

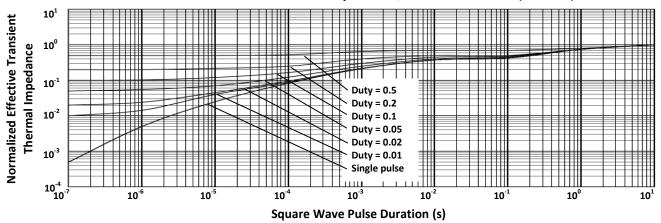




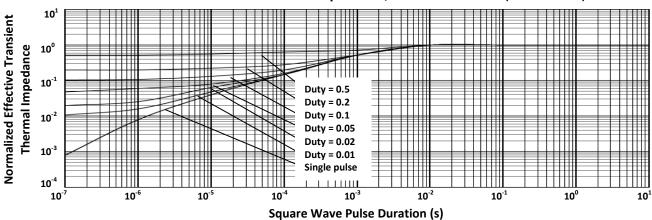
ELECTRICAL CHARACTERISTICS CURVES

 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$

Normalized Thermal Transient Impedance, Junction-to-Case (ITO-220)

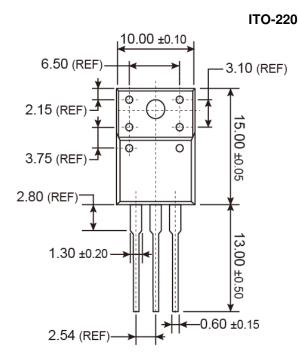


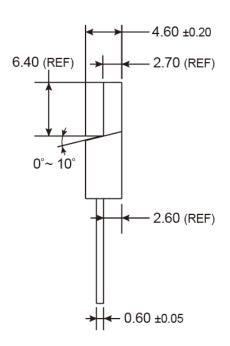
Normalized Thermal Transient Impedance, Junction-to-Case (DPAK/IPAK)





PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)





MARKING DIAGRAM



G = Halogen Free

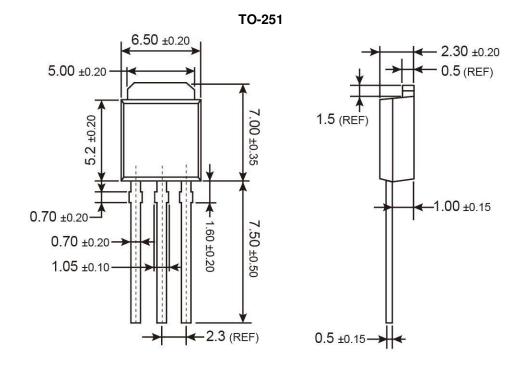
Y = Year Code

WW = Week Code (01~52)

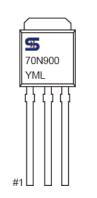
F = Factory Code



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)



MARKING DIAGRAM



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Y = Year Code

M = Month Code

O = Jan P = Feb Q = Mar R = Apr

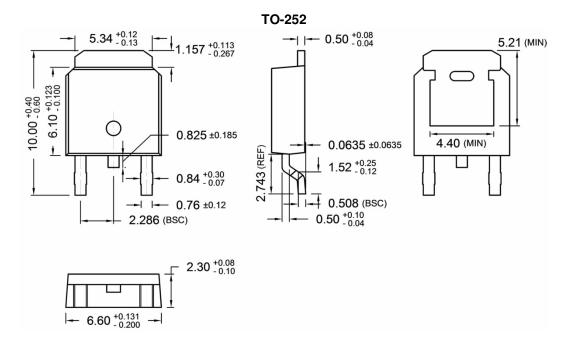
S = May T = Jun U = Jul V = Aug

W = Sep X = Oct Y = Nov Z = Dec

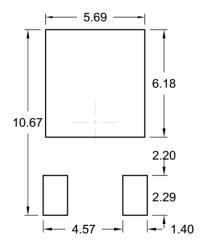
L = Lot Code (1~9, A~Z)
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PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)



SUGGESTED PAD LAYOUT (Unit: Millimeters)



MARKING DIAGRAM



Y = Year Code
M = Month Code
O = Jan P = Feb Q = Mar R = Apr
S = May T = Jun U = Jul V = Aug
W = Sep X = Oct Y = Nov Z = Dec
L = Lot Code (1~9, A~Z)





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